

MIT C320 PnP machine OPERATOR 操作手冊



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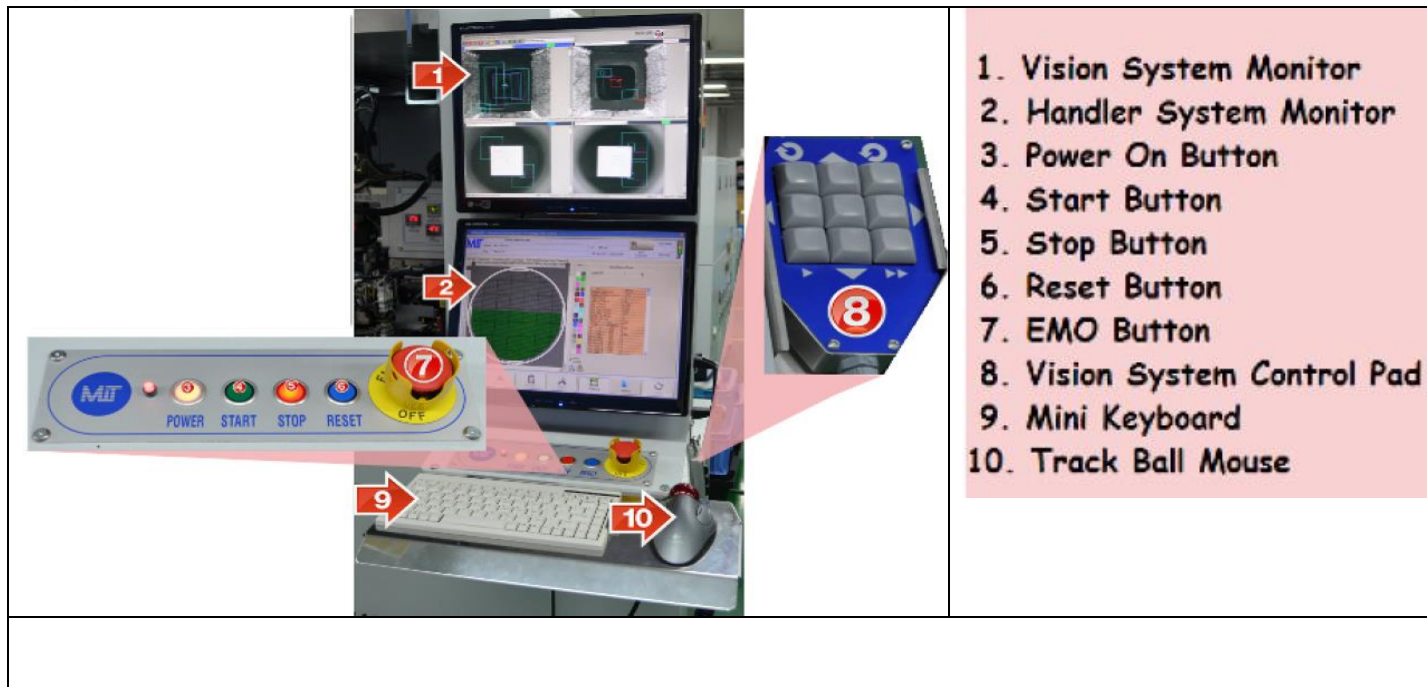
History

Date	Rev.	Comments
2014/12/1	v1	Initial Document

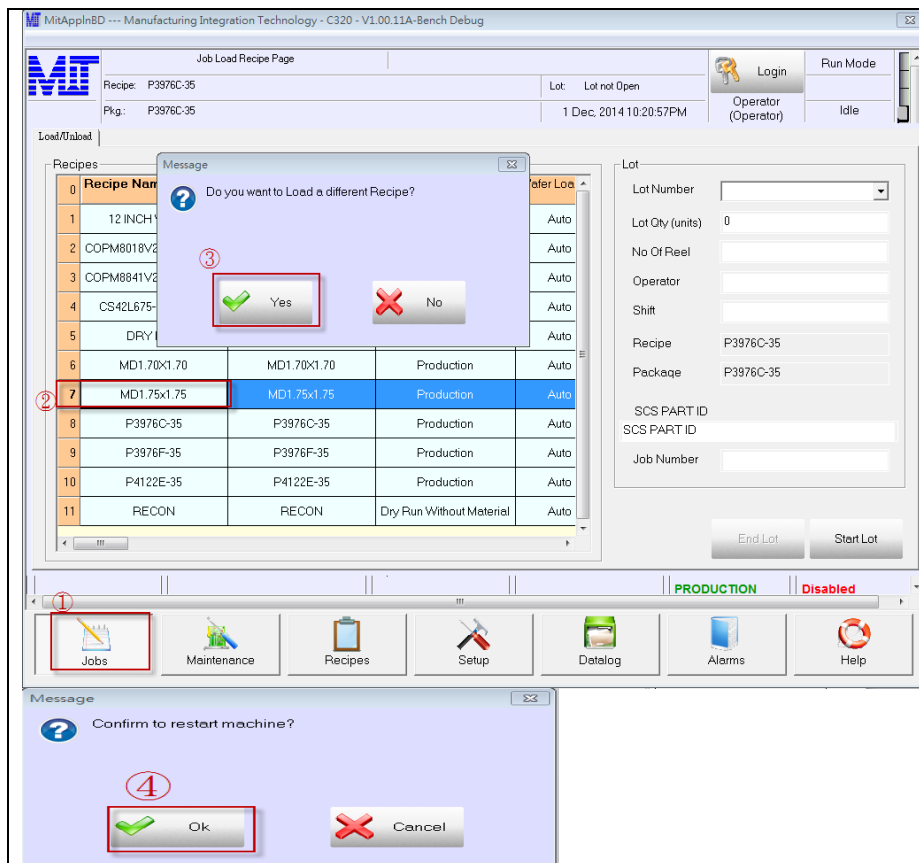
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1. 機台介紹 INTRODUCTION

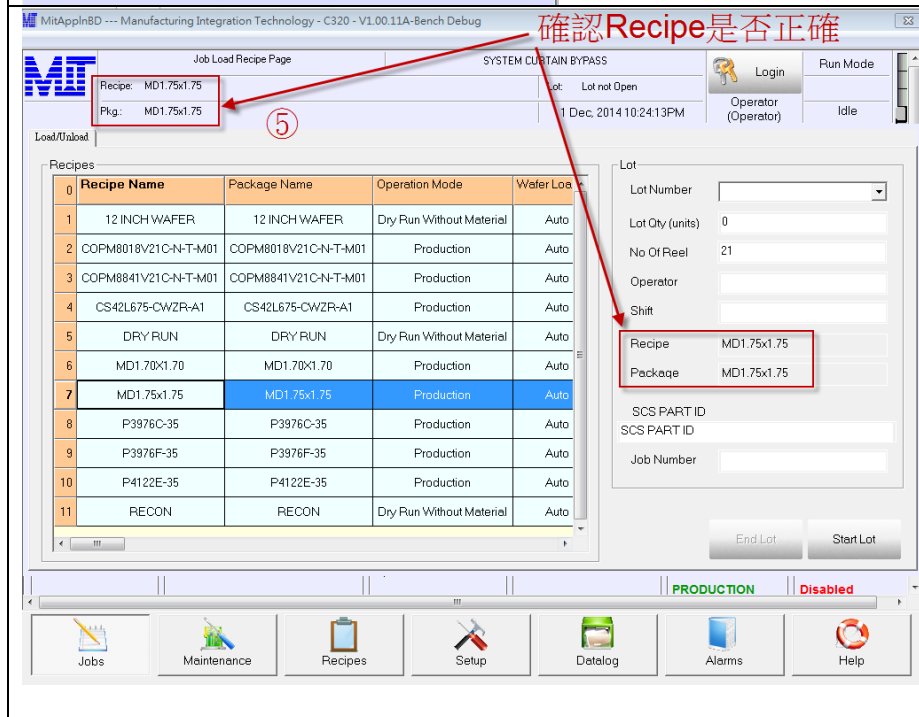
C320 分二台電腦上方為視覺系統(Vision System), 下方為 操作系統(Handler system), 操作界面如下。



2. 載入程式 **DOWNLOAD JOB(RECIPE)**



- ① 點選左下角的 Jobs
- ② 點選所要載入的 Recipe Name
- ③ 點選 Yes 開始載入 Job
- ④ 點選 OK 並按下機台的 Start 鈕，重新開啟機台



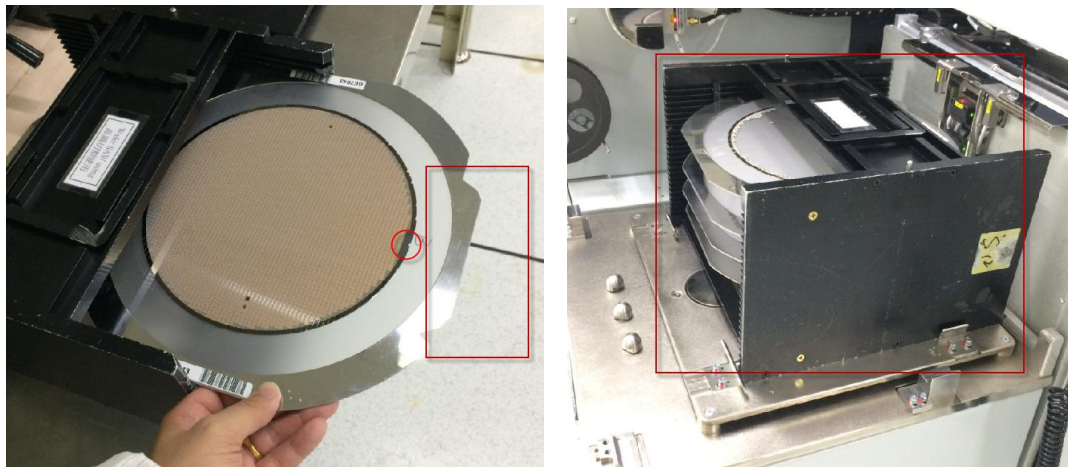
- ⑤ 確認 Recipe 名稱是否正確

3. 生產操作流程 SOP

1. 進入 Jobs 畫面

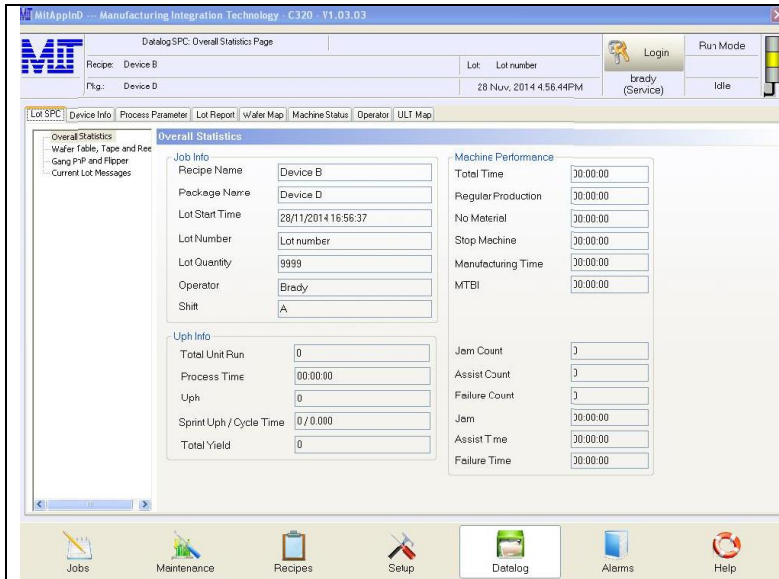


2. 放貨, 注意 Wafer 的方向 缺口 Notch 向外。放入 Cassette, 再將 Cassette 放上機台。

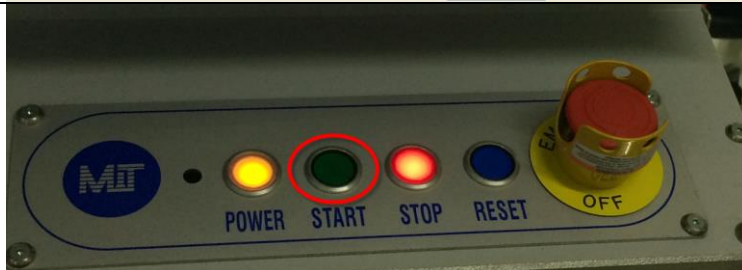


3. 輸入批號 Lot number

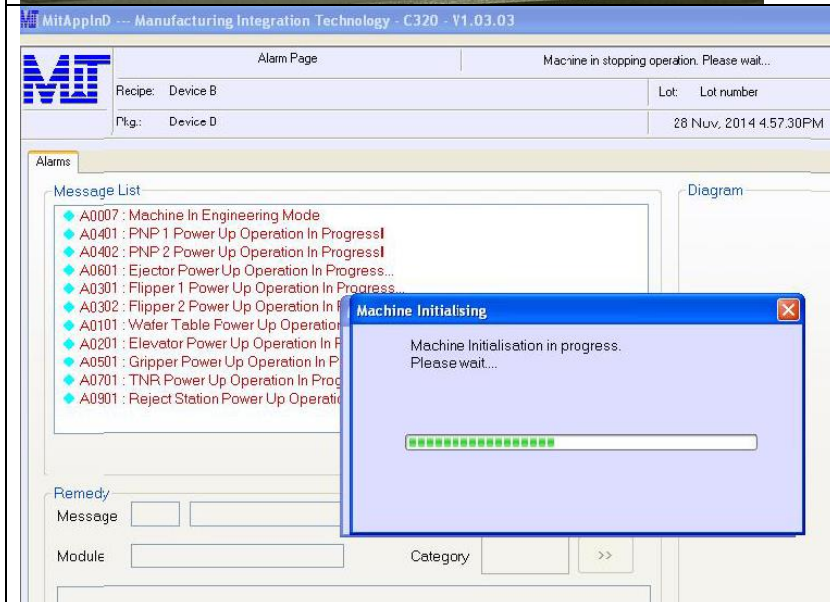
<p>Lot</p> <p>Lot Number <input type="text" value="Lot number"/></p> <p>Lot Qty (units) 9999</p> <p>No Of Reel 10</p> <p>Operatcr Bracy</p> <p>Shift A</p> <p>Recipe Device B</p> <p>Package Device R</p> <p>End Lot Start Lot</p>	<p>Lot number 輸入批號</p> <p>Lot Qty 輸入該批的總數量</p> <p>No of Reel 輸入該批的總 Reel 數</p> <p>Operator 輸入你的工號</p> <p>確認 Recipe 和 Package 是否正確。</p> <p>確認無誤後，按 Start Lot</p>
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當按下 Start Lot 會進入該生產畫面



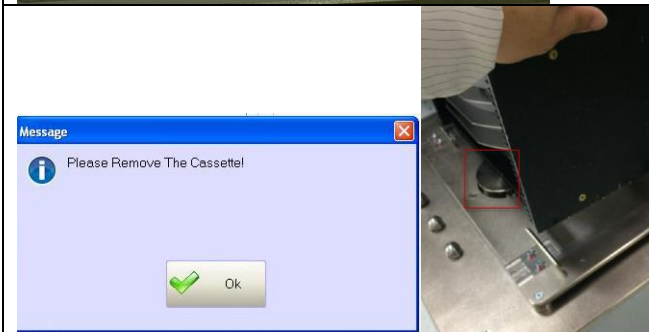
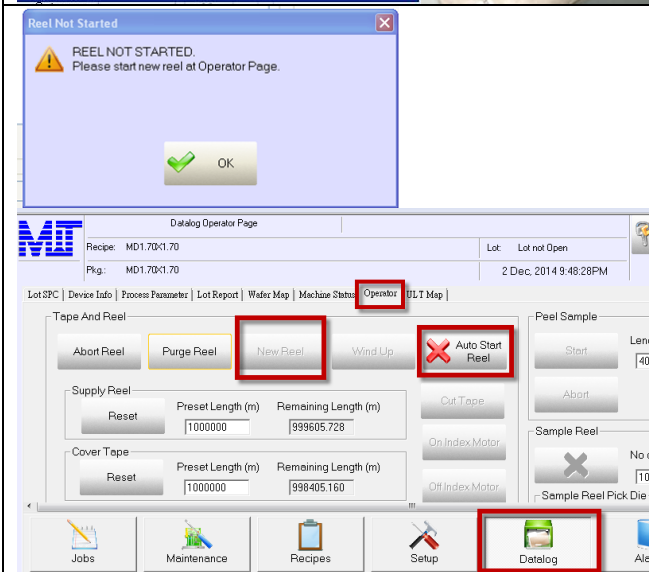
按下 Start 鈕，開始作機台 Homing。



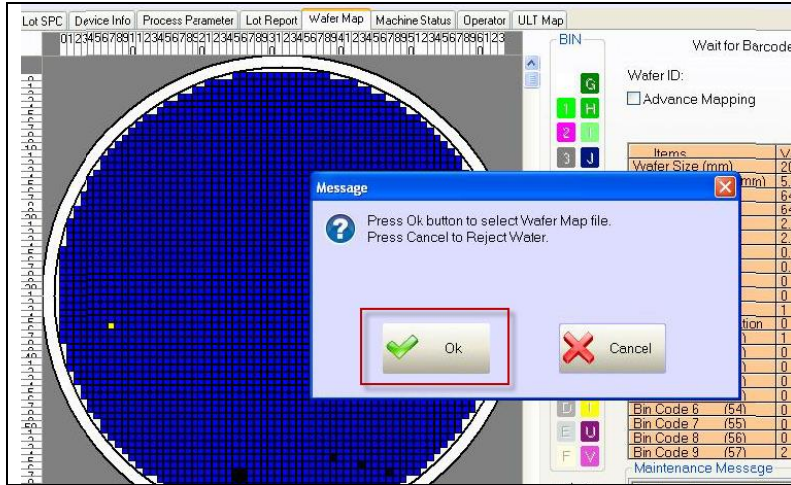
機台作 Homing 中

	<p>機台 Homing 過程中會請你確認一下夾子上是否有 Wafer，確認完，請按 OK。</p>
	<p>STOP 燈亮起，機台無動作和 Error，表示機台 Homing 完成。</p>

4. 開始生產

	<p>按下 Start 鈕，開始生產。</p>
	<p>當出現 Please Remove The Cassette! 請移開 Cassette，拉起 Cassette，再放回即可。後按 OK，然後按下 Start 鈕。</p>
	<p>出現 Reel Not Started Please start new reel at Operator Page。</p> <p>到 Datalog 的 Operator 內。 點選 New Reel，後按機台 START。</p> <p>點選 Auto START Reel 生產完該卷，會自動開始作下一捲。</p>

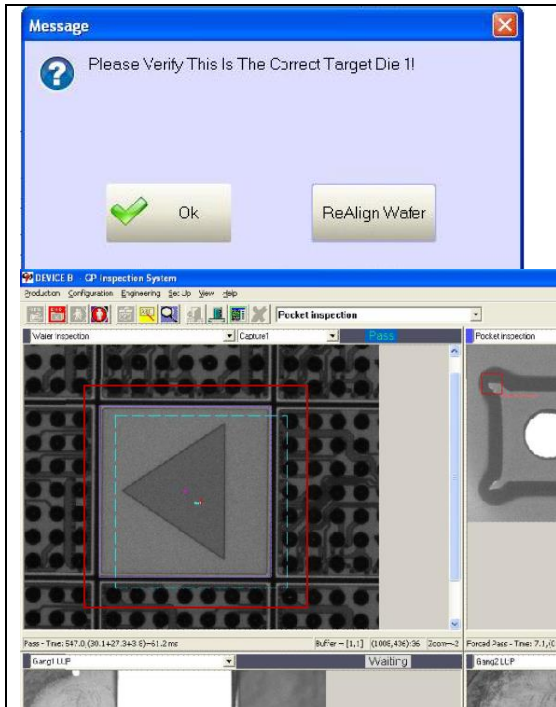
5. 自動載入 Map file



Wafer 進入機台後，會自動抓取 Barcode，並自動載入 Map，

- 如載入失敗。會出現 Press ok button to select Wafer Map file.
- 請點選 OK，
- 後手動點選。

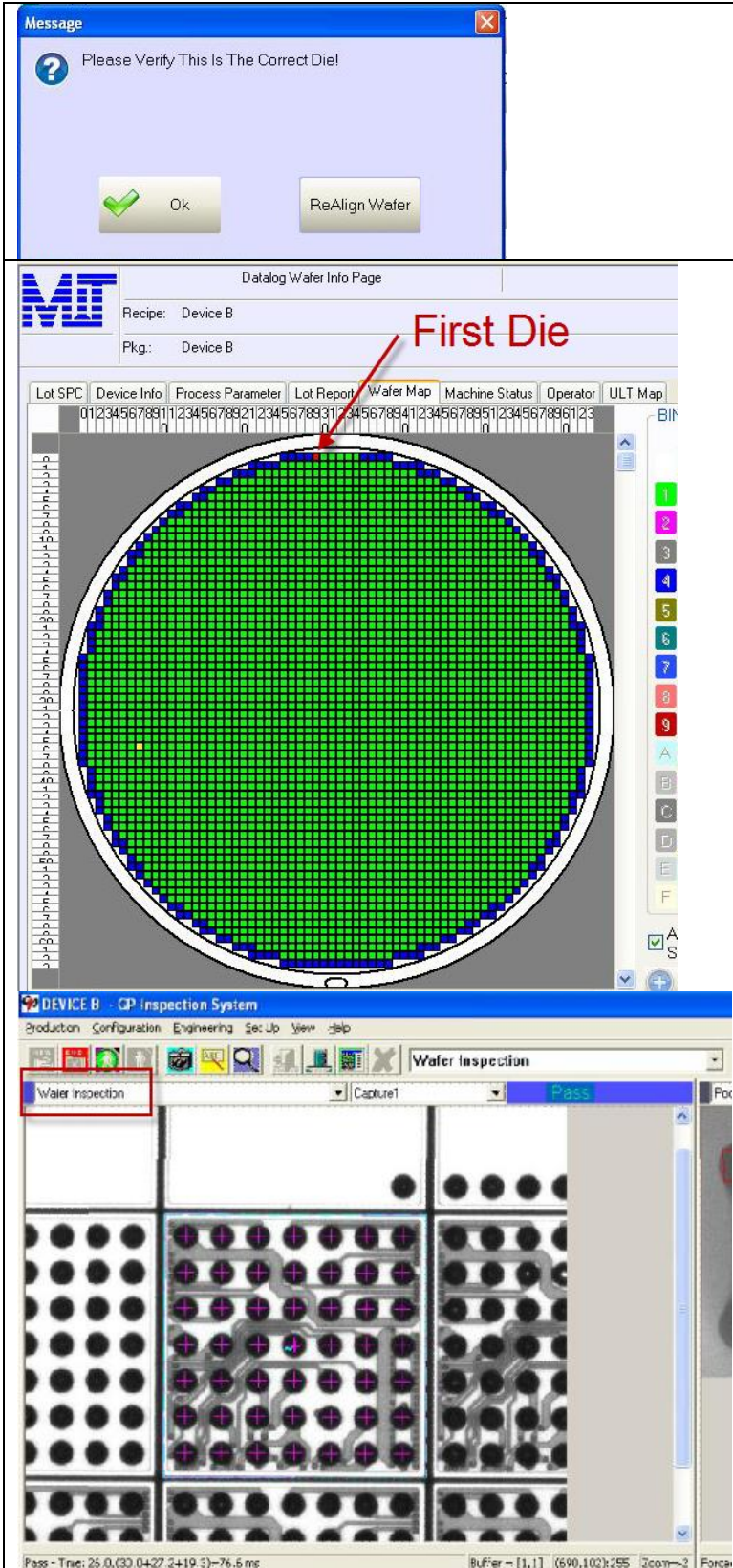
6. Targe Die 確認



當機台出現 Please Verity This is The Correct Target Die!時，

- 請看 Vision 螢幕，確認 Target Die 的位置是否在 Wafer Inspection 內，
- 確認無誤後，按 OK。
- 按下 START。

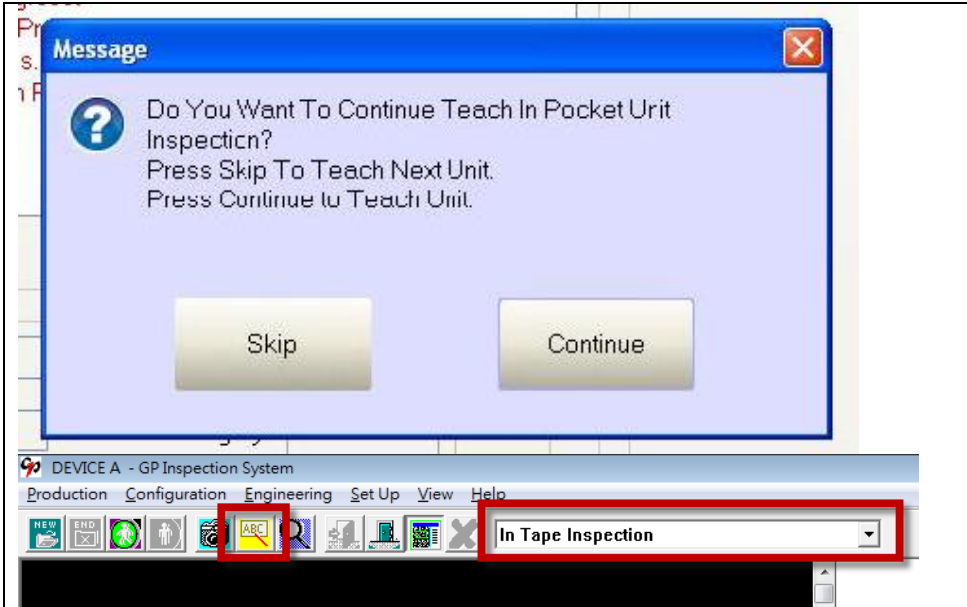

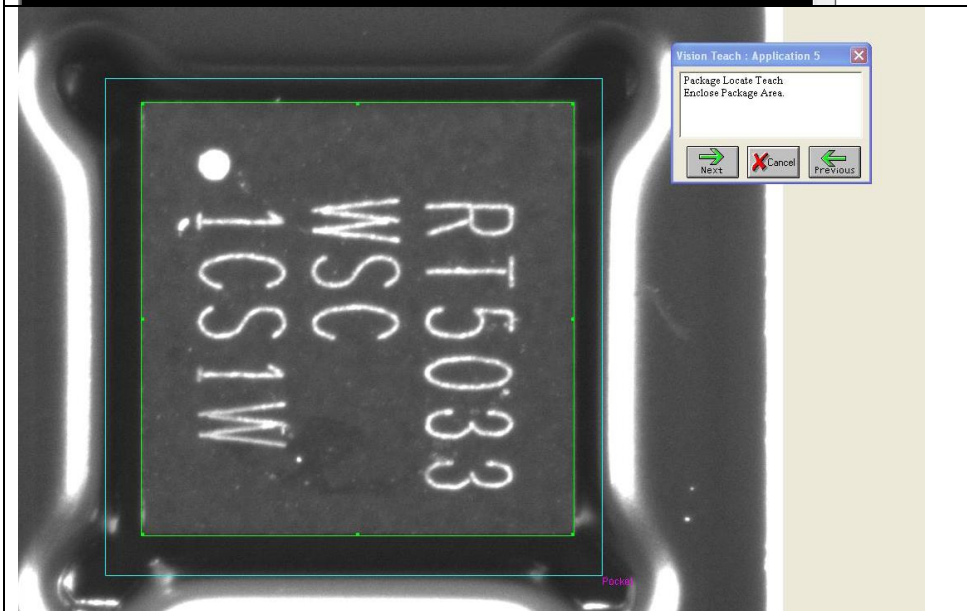
7. First Die 確認。

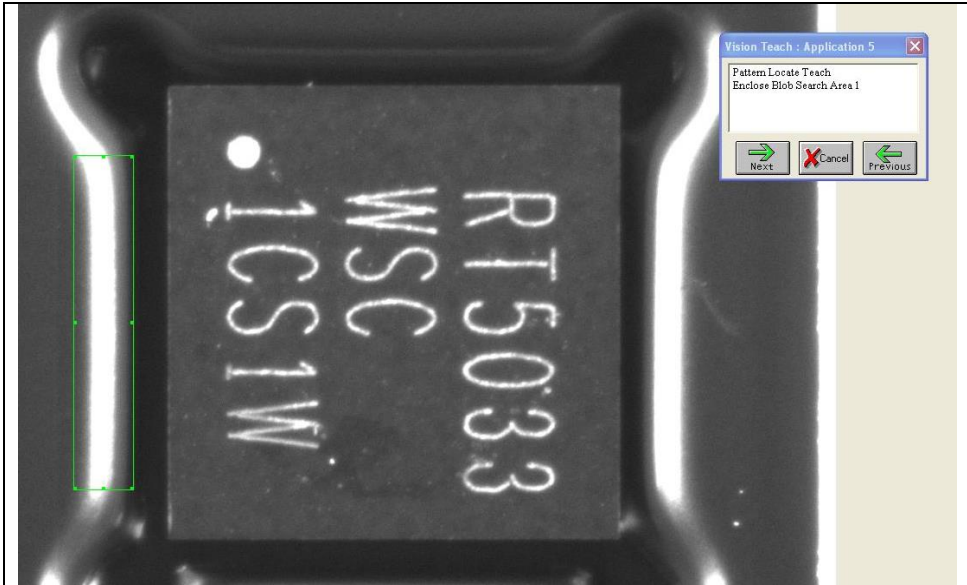
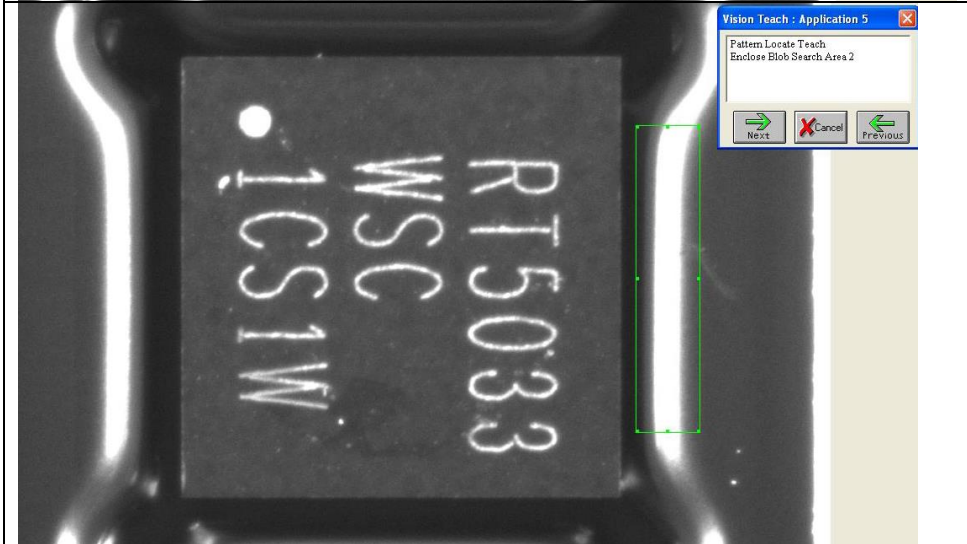


當出現 Please Verify This is the Correct Die!

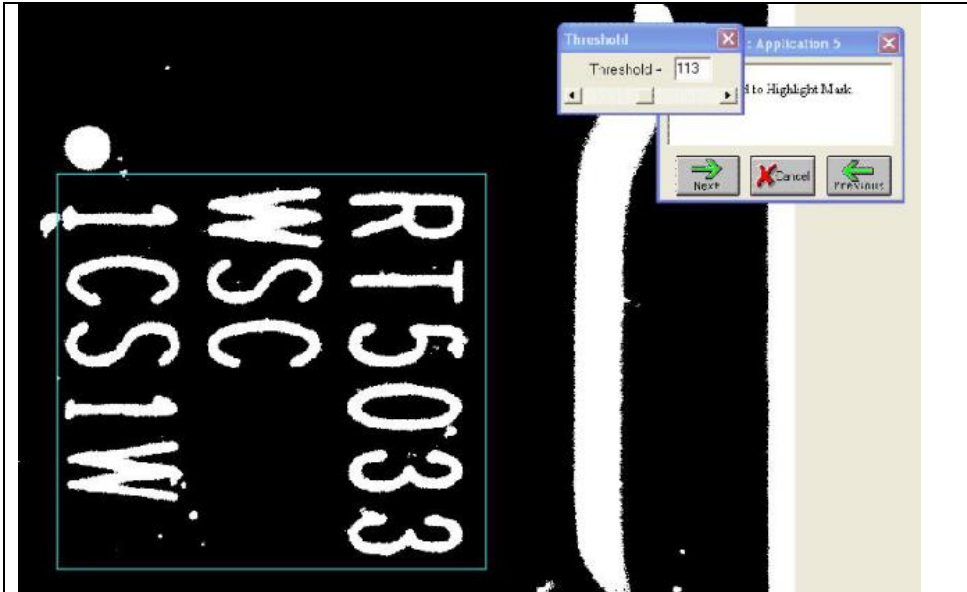
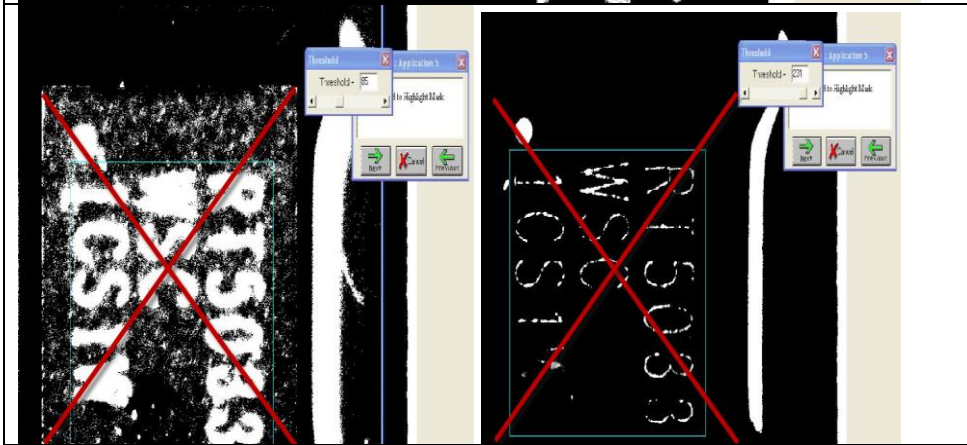
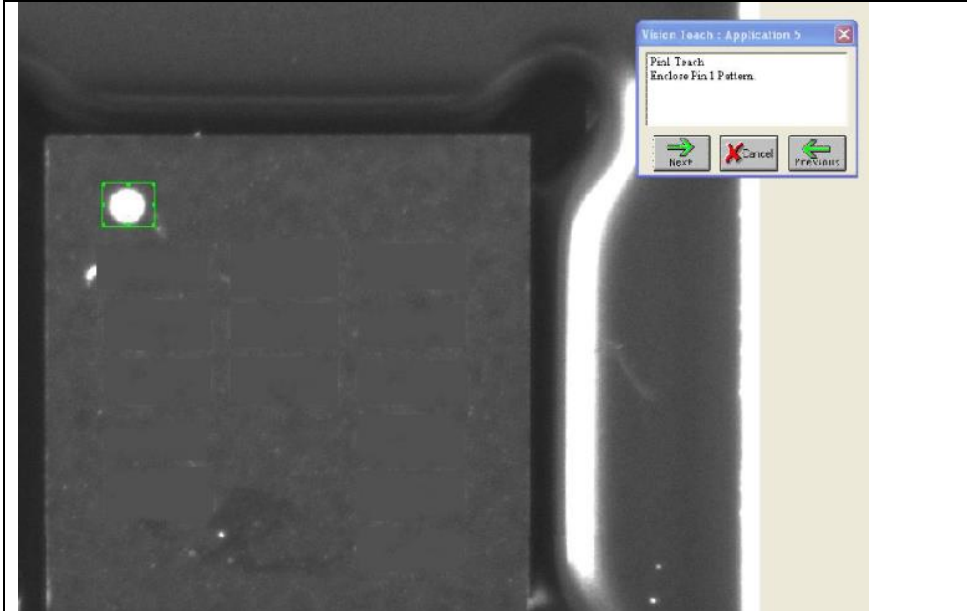
- 確認 Vision 螢幕 First Die 的位置是否和 Map 吻合。
- 確認無誤後，按 OK。
- 再按下機台 START

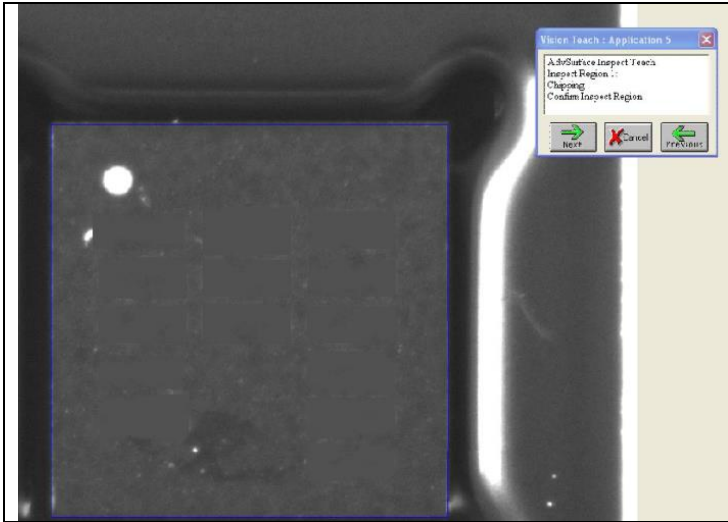
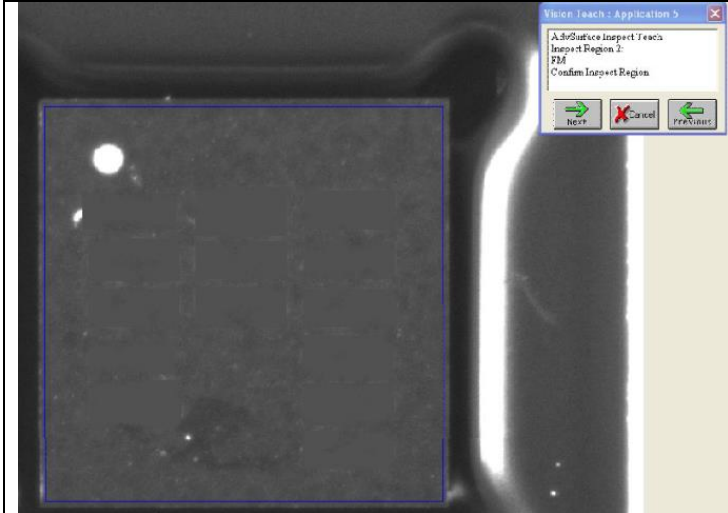
8. 口袋印字教讀 In Tape Pocket Teach。

 <p>The screenshot shows a 'Message' dialog box with a question mark icon and the text: 'Do You Want To Continue Teach In Pocket Unit Inspection? Press Skip To Teach Next Unit. Press Continue to Teach Unit.' Below the text are two buttons: 'Skip' and 'Continue'. Below the dialog box is a software toolbar for 'DEVICE A - GP Inspection System' with a dropdown menu set to 'In Tape Inspection'.</p>	<p>當出現 Teach In pocket Unit Inspection時。 到 Vison 電腦的 In Tape Inspection> </p>
 <p>The screenshot shows a camera view of a die with the text 'R15033', 'MSC', and '1CS1W' printed on it. A green rectangular frame is drawn around the text. A 'Vision Teach : Application 5' dialog box is overlaid on the right side of the image, with the text 'Package Locate Teach. Enclose Package Area.' and three buttons: 'Next', 'Cancel', and 'Previous'.</p>	<p>Package Area Position 框選 Die</p>

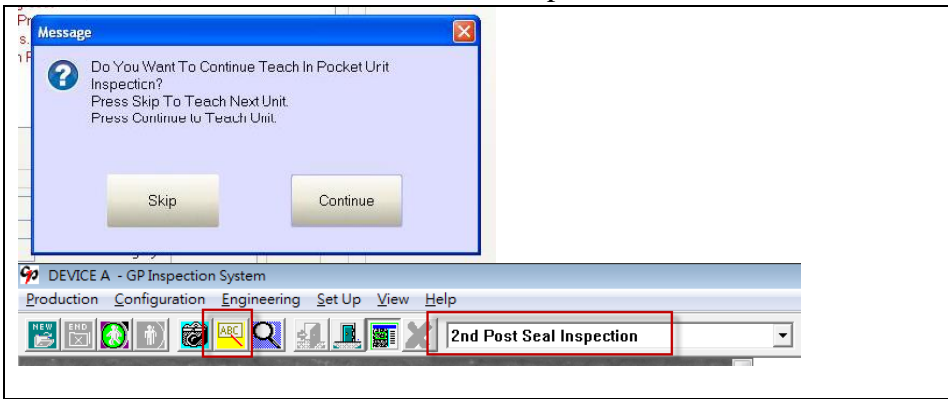

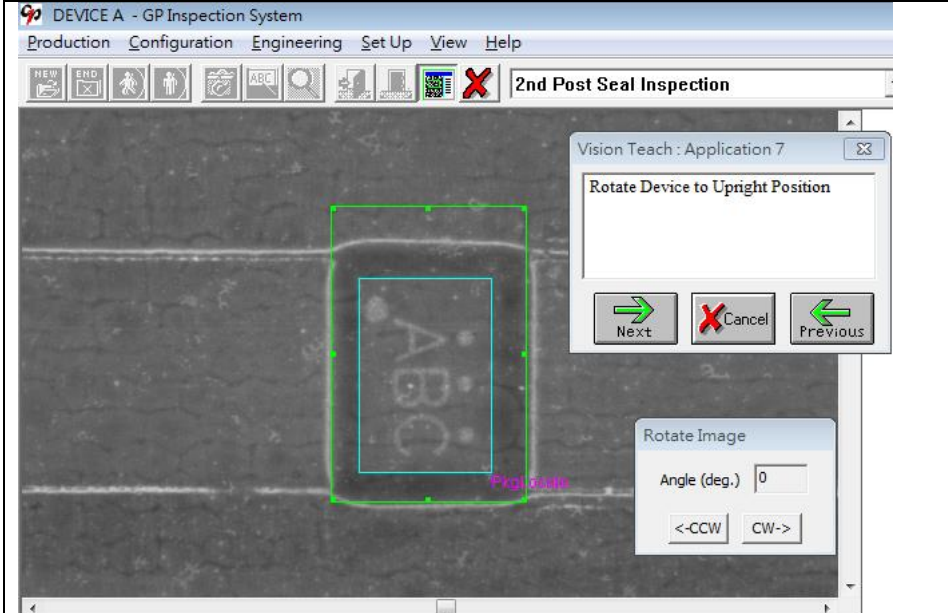
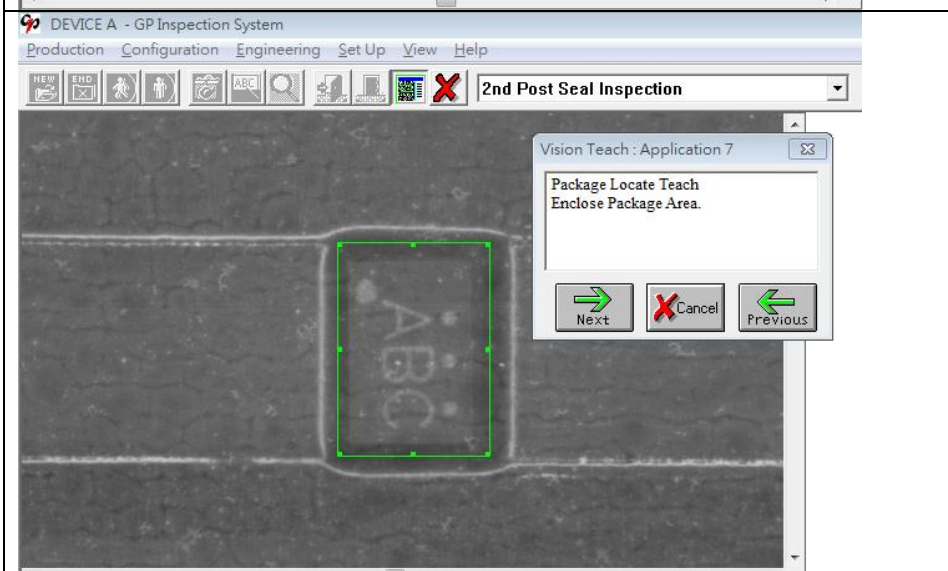
 <p>The screenshot shows a vision system interface for 'Application 5'. The main window displays a grayscale image of a component with the text 'RT5033', 'WSC', and 'ICS1W'. A green rectangular box highlights the left edge of the component. A dialog box titled 'Pattern Locate Teach' is open, showing 'Enclose Blob Search Area 1' and navigation buttons: 'Next', 'Cancel', and 'Previous'.</p>	<p>Pocket Left side 框選左邊口袋邊緣</p>
 <p>The screenshot shows the same vision system interface. The green rectangular box now highlights the right edge of the component. The dialog box is updated to show 'Enclose Blob Search Area 2'.</p>	<p>Pocket Right side 框選右邊口袋邊緣</p>


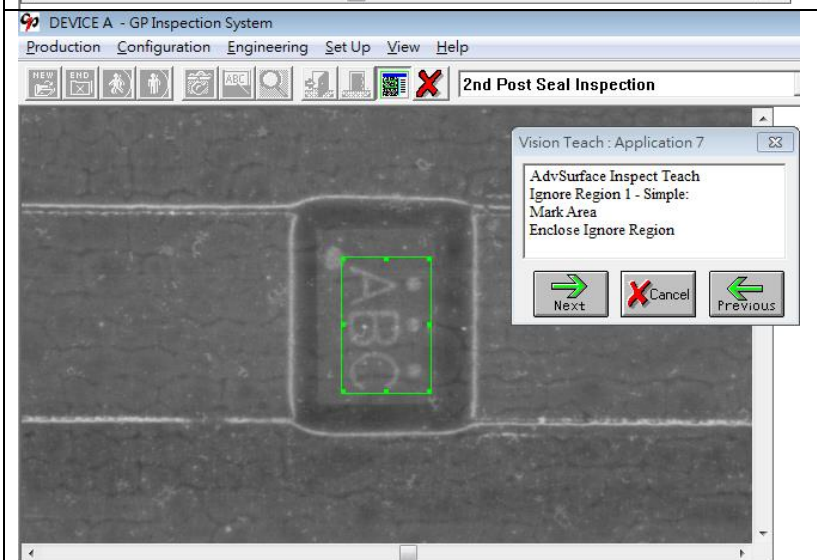
	<p>Pocket Bottom side 框選下方口袋邊緣</p>
	<p>Teach Mark 框選印字範圍</p>

	<p>調整印字門檻</p>
	<p>錯誤的調整方式如左圖</p>
	<p>Teach Pin1 框選 Pin1 的範圍。</p>

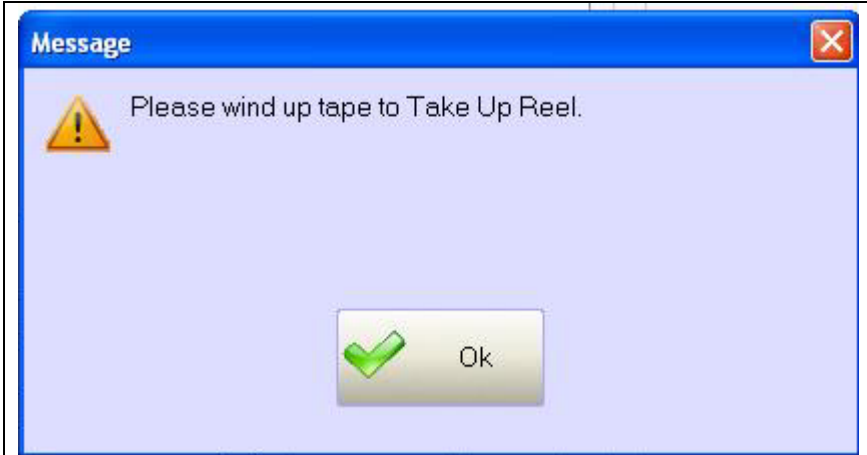
	<p>Chipping Area 確認 Chipping 的檢測範圍</p>
	<p>FM Area 確認 FM 的檢測範圍</p> <p>完成後，Handler 點選 OK，並按下 Start 繼續生產。</p>

9. 口袋內印字教讀 Teach 2nd Post Seal Inspection 。

	<p>當出現 2nd Post seal Inspection 時。</p> <p>到 Vison 電腦</p> <p>2nd Post seal Inspection > </p> <p>作教讀</p>
	<p>Rotate Device 角度調整。</p>
	<p>Enclose Package Area 框選 Die 的位置</p>

	<p>Enclose Pin1 Patten 框選 Pin1</p>
	<p>Mark Area 框選 Mark Area。</p>

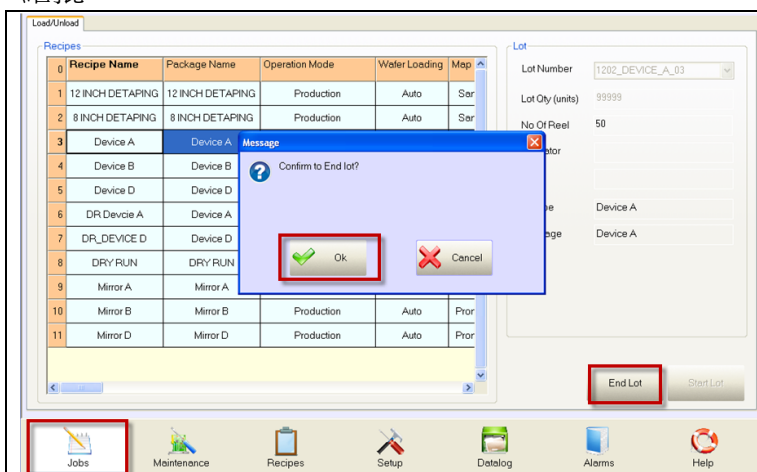
10. Wind up Tape

	<p>當出現 Please wind up tape to Take Up Reel.時。 將帶子穿入 Reel</p>
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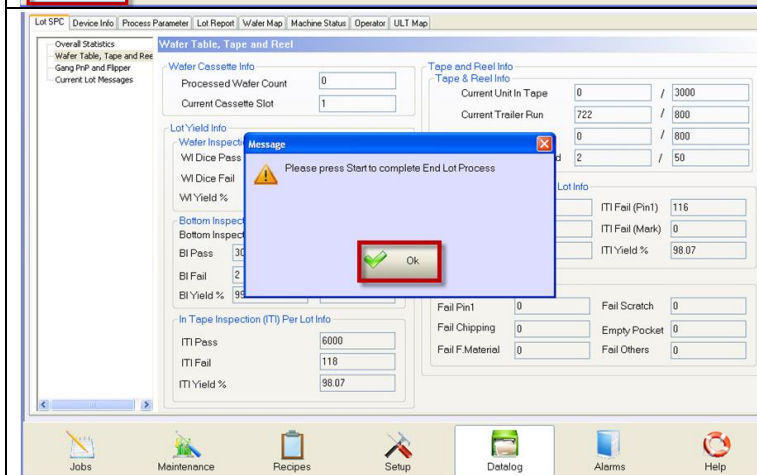
如圖。
穿入 OK 後，按機台 START 繼續生產。

11. 結批 End of Lot

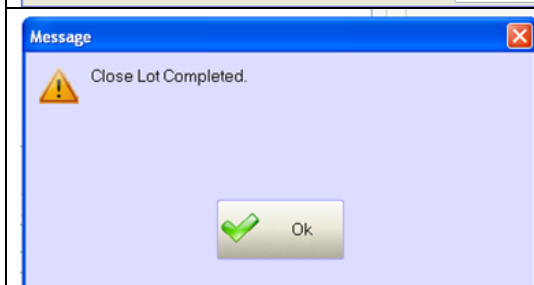


如該批要結束生產。

- 請到 Jobs 內，點選 End Lot。
- 出現 Confirm to End lot 後，按 OK

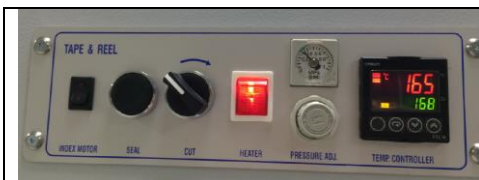


- 出現 Please press Start to complete End Lot Process，再按一次 OK
- 按機台 START 開始結批



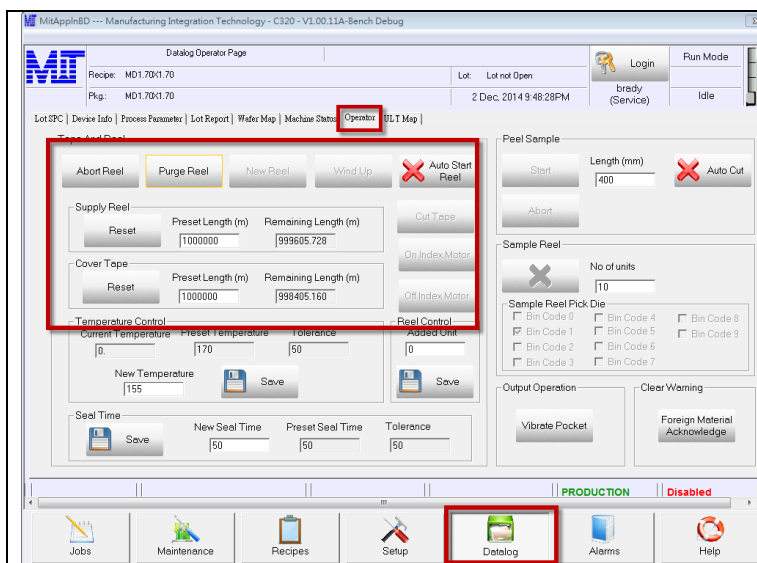
當出現 Close Lot completed，表示機台已完成結批，並將 Wafer 退出。

5. 拉力測試



- 按住 Seal 鈕，機台就會自動導帶，到一定長度後，放開 Seal 鈕
- 轉 Cut，機台會自動切斷帶子。
- 該段帶子即可作拿去作拉力測試

6. TAPE REEL 常用功能說明



- 在 Datelog>Operator 內
- Abort Reel 中止 Reel。
 - Purge Reel 清除 Reel
 - New Reel 開啟 Reel
 - Auto Start Reel 自動開始 Reel
 - Supply Reel Carrier tape 長度確認
 - Cover Tape 長度確認